

## PATENT ASSIGNMENT

Electronic Version v1.1  
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Heping Dai</td> <td>08/02/2013</td> </tr> <tr> <td>Hengchun Mao</td> <td>08/04/2013</td> </tr> <tr> <td>Zhihua Liu</td> <td>08/12/2013</td> </tr> <tr> <td>Zhaozheng Hou</td> <td>08/02/2013</td> </tr> </tbody> </table>		Name	Execution Date	Heping Dai	08/02/2013	Hengchun Mao	08/04/2013	Zhihua Liu	08/12/2013	Zhaozheng Hou	08/02/2013		
Name	Execution Date												
Heping Dai	08/02/2013												
Hengchun Mao	08/04/2013												
Zhihua Liu	08/12/2013												
Zhaozheng Hou	08/02/2013												
RECEIVING PARTY DATA													
<table border="1"> <tr> <td>Name:</td> <td>FutureWei Technologies, Inc.</td> </tr> <tr> <td>Street Address:</td> <td>5340 Legacy Drive</td> </tr> <tr> <td>Internal Address:</td> <td>Suite 175</td> </tr> <tr> <td>City:</td> <td>Plano</td> </tr> <tr> <td>State/Country:</td> <td>TEXAS</td> </tr> <tr> <td>Postal Code:</td> <td>75024</td> </tr> </table>		Name:	FutureWei Technologies, Inc.	Street Address:	5340 Legacy Drive	Internal Address:	Suite 175	City:	Plano	State/Country:	TEXAS	Postal Code:	75024
Name:	FutureWei Technologies, Inc.												
Street Address:	5340 Legacy Drive												
Internal Address:	Suite 175												
City:	Plano												
State/Country:	TEXAS												
Postal Code:	75024												
PROPERTY NUMBERS Total: 1													
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13957080</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13957080								
Property Type	Number												
Application Number:	13957080												
CORRESPONDENCE DATA													
<p>Fax Number: 9727329218  <i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i></p> <p>Phone: (972)732-1001        Email: docketing@slater-matsil.com        Correspondent Name: Slater &amp; Matsil, L.L.P.        Address Line 1: 17950 Preston Road        Address Line 2: Suite 1000        Address Line 4: Dallas, TEXAS 75252</p>													
ATTORNEY DOCKET NUMBER:	HW 83474731US02												
NAME OF SUBMITTER:	Latoya Jenkins												

CH \$40.00 13957080

Signature:	/Latoya Jenkins/
Date:	09/03/2013
Total Attachments: 2 source=42G6475#page1.tif source=42G6475#page2.tif	

**ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

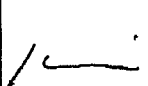

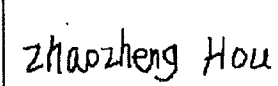
WHEREAS, FutureWei Technologies, Inc. ("FutureWei"), a corporation organized and existing under the laws of Texas, with its principal office at 5340 Legacy Drive, Suite 175, Plano, TX 75024, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said FutureWei, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said FutureWei, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to FutureWei, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said FutureWei, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said FutureWei, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Apparatus for PWM Gate Drive Circuit			
SIGNATURE OF INVENTOR AND NAME	 Heping Dai	 Hengchun Mao	Zhihua Liu	 Zhaozheng Hou
DATE	08/02/13	8/4/13		August 2, 2013
RESIDENCE (City, State)	Plano, TX	Plano, TX	Shenzhen, P.R. China	Shenzhen, P.R. China

**ASSIGNMENT**

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made; and

WHEREAS, FutureWei Technologies, Inc. ("FutureWei"), a corporation organized and existing under the laws of Texas, with its principal office at 5340 Legacy Drive, Suite 175, Plano, TX 75024, is desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said FutureWei, its successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said FutureWei, as assignee of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to FutureWei, its successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said FutureWei, or to its successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee company, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said FutureWei, its successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Apparatus for PWM Gate Drive Circuit			
SIGNATURE OF INVENTOR AND NAME	Heping Dai	Hengchun Mao	<i>Liu Zhihua</i> Zhihua Liu	Zhaozheng Hou
DATE			2013.08.12	
RESIDENCE (City, State)	Plano, TX	Plano, TX	Shenzhen, P.R. China	Shenzhen, P.R. China